

BRBSS84Q
Rev.A Mar.-2023

SOT-23 P
P-CHANNEL MOSFET in a SOT-23 Plastic Package.

F0P RV WW0

4333Y

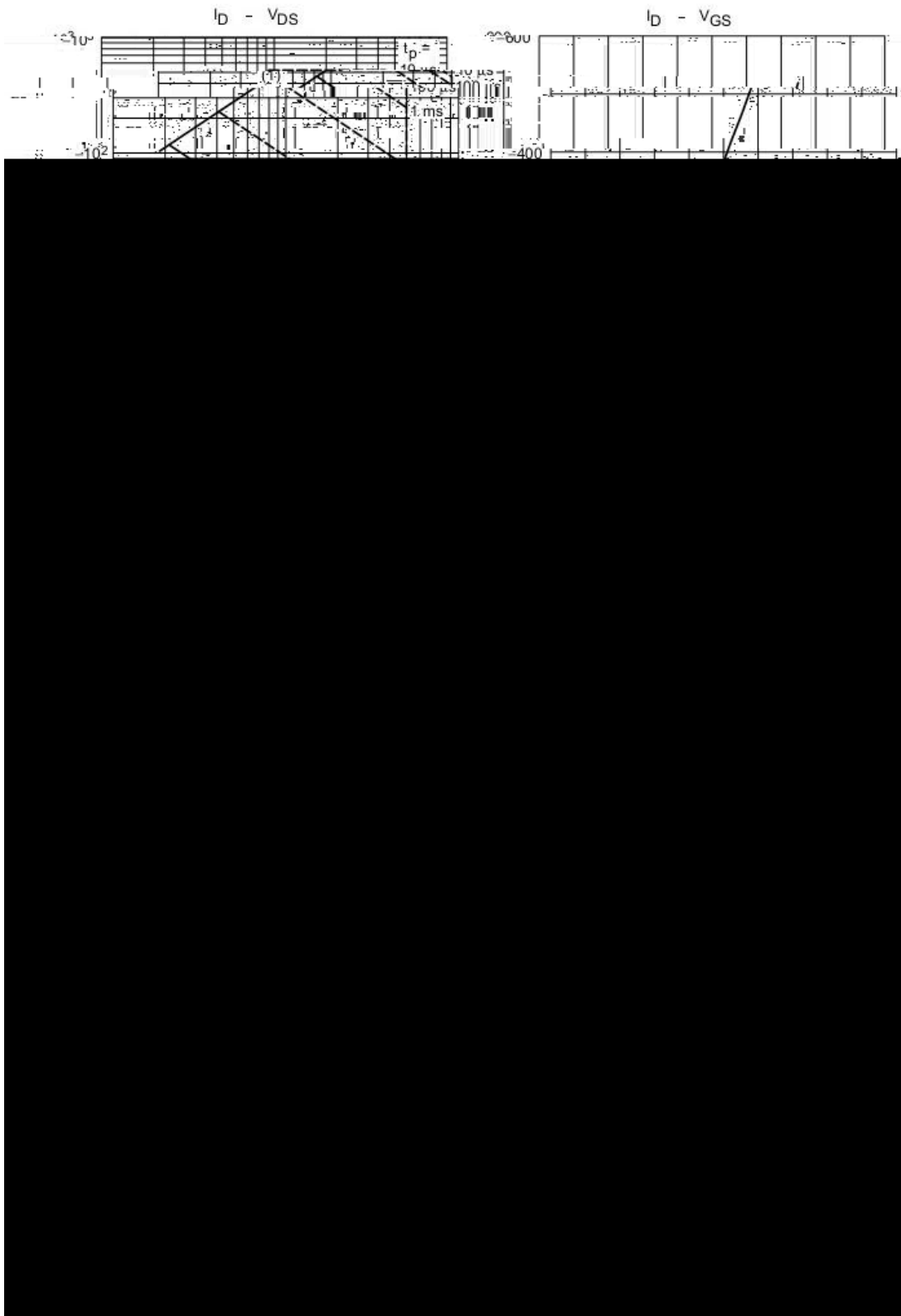
DHF0T434

Low threshold voltage, Direct interface to C-MOS, TTL etc, High-speed switching,ESD Improved

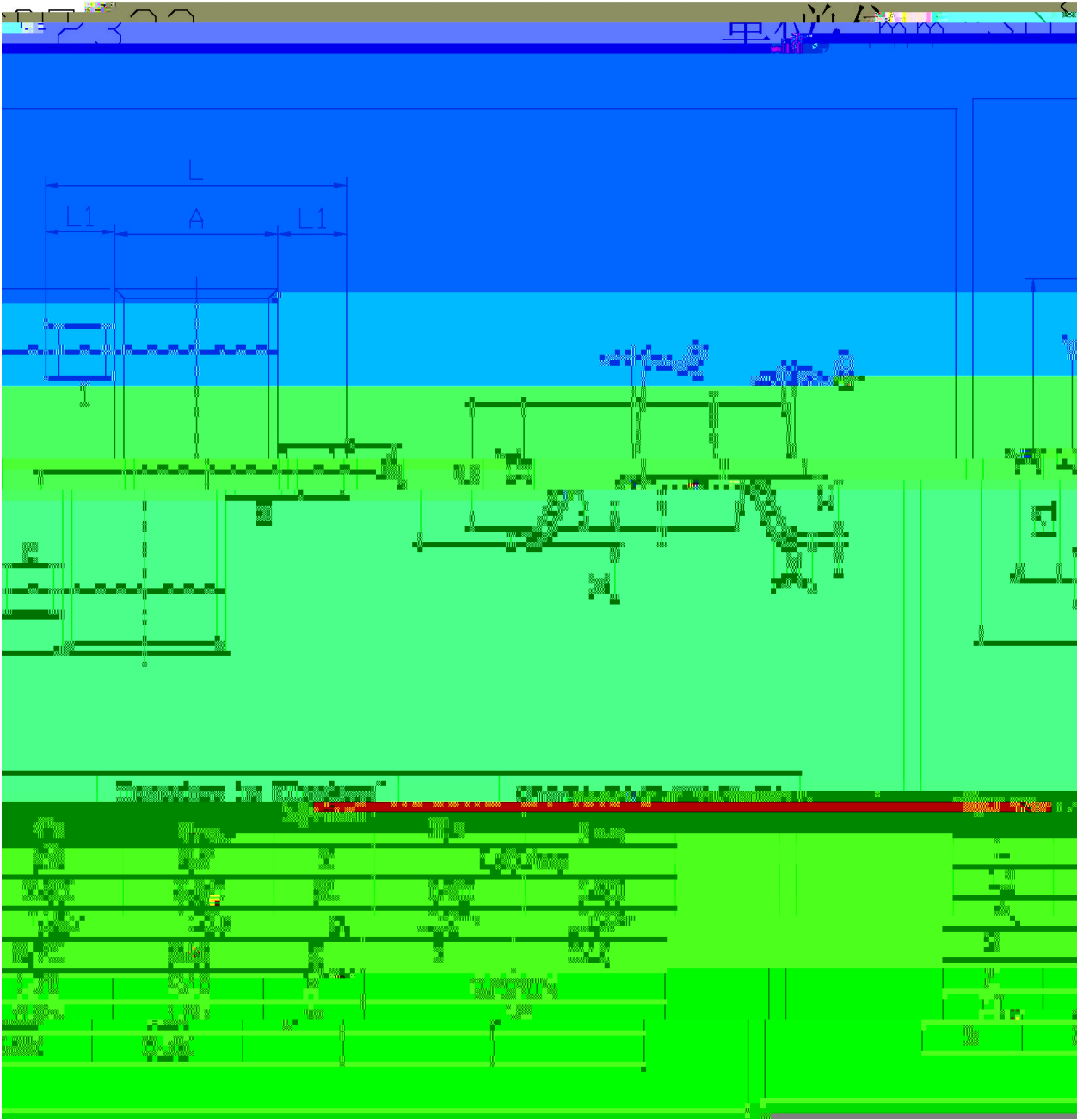
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	-50	V
Drain Current – Continuous	I_D	-130	mA
Peak Drain Current	I_{DM}	-520	mA
Gate-Source Voltage	V_{GSS}	± 20	V
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	500	/W
Storage Temperature Range	T_{stg}	-65 to 150	
Junction Temperature Range	T_j	150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain–Source Breakdown Voltage	V_{DSS}	$V_{GS}=0V$ $I_D=-10\mu A$	-50			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=-250\mu A$	-0.8		-2.0	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS}=0V$ $V_{DS}=-40V$			-100	nA
		$V_{GS}=0V$ V_{DS}				

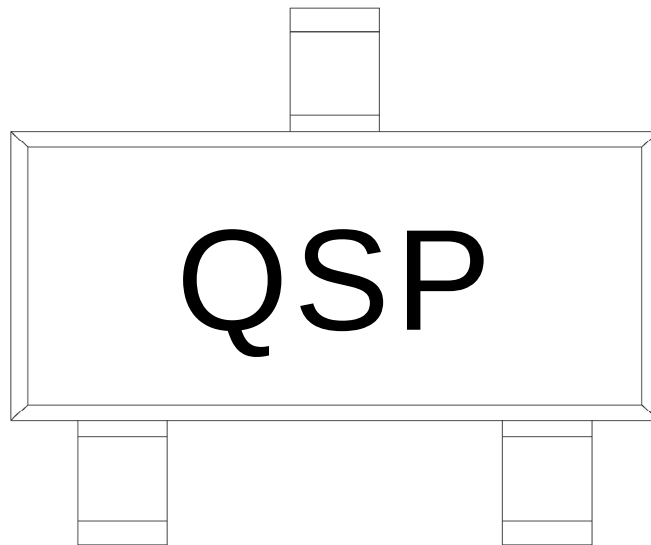
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



T

SP

Note:

Q: Automobile halogen-free product Code

SP: Product Type.

() / **Temperature Profile for IR Reflow Soldering(Pb-Free)**

Note:

- | | | | |
|---|--------------|--------------|---|
| 1 | 150 ~ 200℃ | 60 ~ 120sec; | 1.Preheating:150~200℃, Time:60~120sec. |
| 2 | 255 ± 5℃ | 5 ± 0.5sec; | 2.Peak Temp.:255 ± 5℃, Duration:5 ± 0.5sec. |
| 3 | 2 ~ 10℃/sec. | | 3.Cooling Speed: 2~10℃/sec. |

/ **Resistance to Soldering Heat Test Conditions**

260 ± 5℃	10 ± 1 sec.	Temp.:260 ± 5℃	Time:10 ± 1 sec
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/ **Packaging SPEC.**

/ REEL

Package Type